



COMPUTEX TAIPEI: INNOVATION FORUM 2011

Changing User Needs Step up Progress of Smart Devices	21
Computex - Innovation Forum Agenda	22
STMicroelectronics Takes Aim at Energy Efficiency, Healthcare, Security	23
Qualcomm's Snapdragon Redefines Mobile Computing	24
NEC Merges Innovation, ICT for Industrial, Regional Growth	25
With Powerful GPUs, NVIDIA Shapes Mobile Gaming Landscape	26
NTT DOCOMO Spurs Mobile Broadband Innovation in Information Society	27
Under LTE, Renesas Mobile Drives Smartphone Evolution	28
NXP's Identification Solutions Impact Varied Industry Fields	30
MasterImage Powers Evolution of Glass-Less 3D Viewing	32
Ericsson Speeds up Connectivity with Mobile Broadband Modules	34
Ralink's Innovative Wi-Fi Chip Fuels PC's Role in Connectivity	36
HD-PLC Alliance Tracks Green Road for Power Line Solutions	38
With WHDI, Amimon Amplifies HD Mobile Viewing to Big Screen	40
3D Tile Format Offers Best Way to Broadcast 3D TV	42
InvenSense Taps MotionProcessing as Common Interface for Smart TVs	44
Technology Innovations Spur New Market, Service Models	46

CORPORATE CLOSE-UP

TANAKA's Product Lineup Supports Production of White LEDs	49
TANAKA's Product Lineup for LED Manufacturing Processes	50

ASIA ELECTRONICS INDUSTRY (ISSN 1342-422X) is published monthly by Dempa Publications, Inc., 1-11-15 Higashi Gotanda, Shinagawa-ku, Tokyo 141-8715, Japan Tel: +81-3-3445-6111 Fax: +81-3-3447-4666. Editorial e-mail: may@dempa.co.jp; Subscription e-mail: circmnl@pltdsl.net. The magazine is distributed free to qualified subscribers in ASEAN countries (Thailand, Indonesia, The Philippines, Malaysia, Singapore, Brunei, Vietnam, Myanmar, Cambodia and Laos), as well as Korea, Taiwan and Hong Kong.

Paid air mail subscription is available to non-qualified subscribers in the Asian and Pacific regions for US\$150 per year and US\$260 for two years. For other areas, air mail subscription fees are US\$160 per year and US\$280 for two years. Paid subscription is accepted at <http://aei.dempa.net/paidsub/subscription.html>

Send address corrections to Dempa Publications, Inc., c/o Quantum Solutions (HK) Ltd. Unit 3-6, G/F Pacific Trade Centre, 2 Kai Hing Road, Kowloon Bay, Kowloon, Hong Kong

President & Publisher: Tetsuo Hirayama

Copyright © 2011 by Dempa Publications, Inc.

All rights reserved. The contents of this magazine may not be reproduced in whole or in part without the prior permission of the copyright owner. Printed in Hong Kong.

IN THE KNOW: SOLDERING TIPS

Length, Internal Specification of Soldering Tips Gauge Quality	52
--	----

SPECIAL REPORT

Advanced Microcontrollers	
MCU Technologies Evolve as Market Expands	54
NXP Focuses on Speed, Function in Small, Power-Saving MCUs	55
Fujitsu Semiconductor's MCUs Step up Performance, Ease-of-Use	58
ST Microelectronics Strengthens Deployment of STM32 MCUs	59
ROHM Designs Chip Set for Intel Atom E600 Series Processor	61

TECHNOLOGY FOCUS

Compact Antenna Couplers by Murata Suit TransferJet Devices	64
---	----

SMTs: IN REVIEW

	66
--	----

COMPONENT MATERIALS

	67
--	----

TEST AND MEASUREMENTS

	72
--	----

MANUFACTURING FRONT

Low Power Use Defines Citizen Electronics' AC-Driven LED Lighting Modules	74
---	----

INDUSTRY REPORT

High-Volume Communication, Data Traffic Buoy Optical Measuring Tools Market	78
---	----

DEPARTMENTS

AEI News	14
Techwatch	18
Product News	80

Taiwan: International Dempa Trade Co., Ltd., 7F-1, No. 36, Nanking W. Rd., Taipei, Taiwan, Tel: +886-2-2558-1817 Fax: +886-2-2555-6428 **Korea:** Dempa Publications, Seoul Office, Masters Tower, Room 1404, 553 Dohwa-dong, Mapo-ku, Seoul, Korea, 121-040, Tel: +82-2-714-2983 Fax: +82-2-714-2984 **Philippines:** Dempa Publications, Inc. - Regional Headquarters, Herrera Tower, Room 2510, 98 V.A. Rufino Street, Salcedo Village, Makati City, Philippines, Tel: +63-2-845-0906 Fax: +63-2-845-1829